

JP08125066

RESIN-SEALED SEMICONDUCTOR DEVICE AND LEAD FRAME USED FOR IT, AND MANUFACTURE OF RESIN-SEALED SEMICONDUCTOR DEVICE

DAINIPPON PRINTING CO LTD

Inventor(s): YAGI YUTAKA ; MORITA MICHIIHIKO

Application No. 06284536 , Filed 19941026 , Published 19960517

Abstract:

PURPOSE: To raise occupancy rate of a chip and to miniaturize a semiconductor device by fixing a plurality of lead parts wherein an inside terminal part and an outside terminal part are integrated to a semiconductor element surface through an insulation adhesive layer and by connecting an outside electrode part consisting of solder to an outside terminal part.

CONSTITUTION: A plurality of lead parts 102 wherein an inside terminal part 102A, an outside terminal part 102B and a connection lead part 102C are integrated are sealed and provided to a terminal side surface of a semiconductor element 101 through an insulation adhesive layer 104. An outside electrode 106 consisting of solder for mounting on a circuit substrate, etc., is connected to an outside terminal part 102B of each of a plurality of leads 102. At least a part of the outside electrode 106 consisting of solder is provided to be exposed to an outside from a resin part 105. Thereby, it is possible to raise occupation rate of a chip in a package size of a semiconductor device to correspond to miniaturization of a semiconductor device and to reduce the mounting area of the semiconductor device on a circuit substrate.

Int'l Class: H01L02312 H01L02328

MicroPatent Reference Number: 001265542

COPYRIGHT: (C) 1996 JPO

